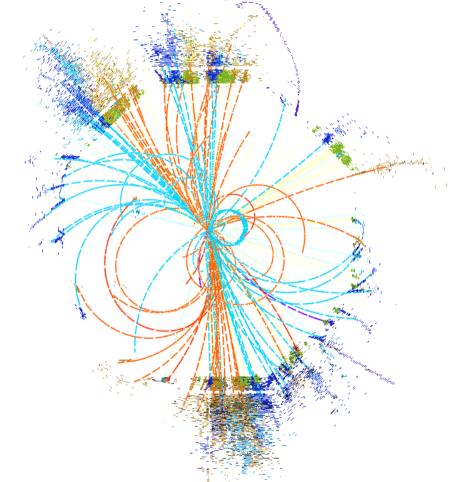


Detectors at CLIC



Philipp Roloff (CERN) on behalf of the CLIC physics and detector study



Joint Instrumentation Seminar, DESY Hamburg, 20/01/2012



Outline



- The CLIC accelerator
- Physics at CLIC
- Detector requirements
- The CLIC_ILD and CLIC_SiD detectors
 - Vertex detectors
 - Tracking
 - Calorimetry
- Background suppression and event reconstruction





The CLIC accelerator

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CLIC and ILC



 e^+e^- collisions at high energies \rightarrow linear accelerators



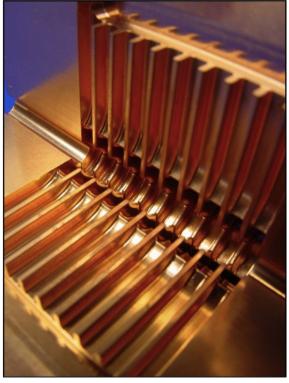
International Linear Collider (ILC):

- Based on superconducting RF cavities (like XFEL)
- Gradient: 32 MV/m
- Energy: 500 GeV, upgradable to 1 TeV
- Detector studies focussed mostly on up to 500 GeV, work for 1 TeV ongoing

Compact Linear Collider (CLIC):

- Based on 2-beam acceleration scheme
- Operated at room temperature
- Gradient: 100 MV/m
- Energy: <u>3 TeV</u>, staged construction in steps starting from few hundred GeV possible
- Detector study focusses on 3 TeV, lower energies will be studies soon

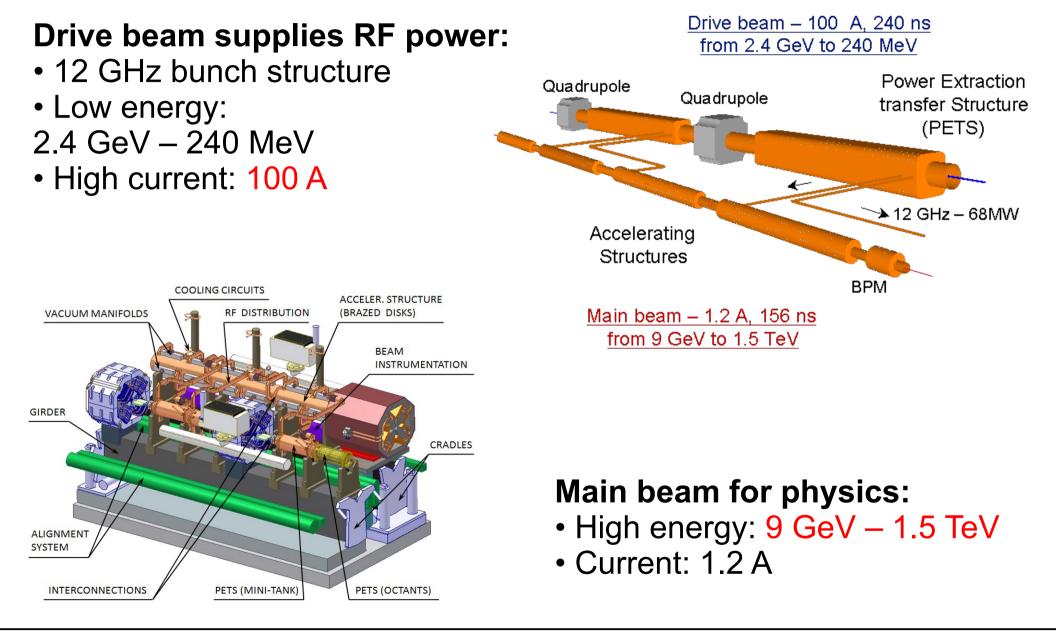
Luminosities: few 10³⁴ cm⁻²s⁻¹





2-beam acceleration scheme

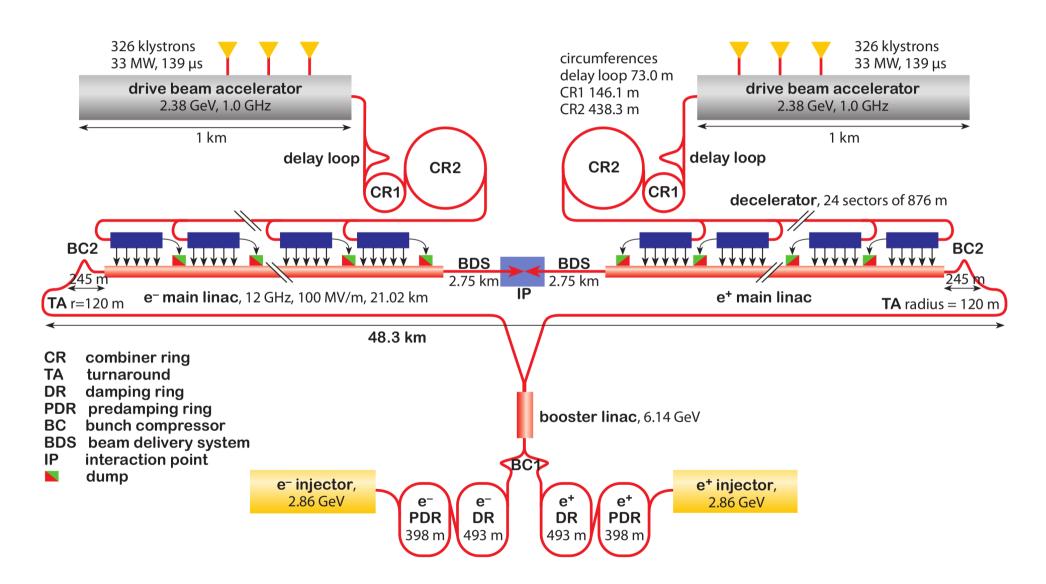






CLIC accelerator complex





CERN

CLIC physics and detector CDR

CLIC provides the potential for e+e- collisions up to \sqrt{s} = 3 TeV:

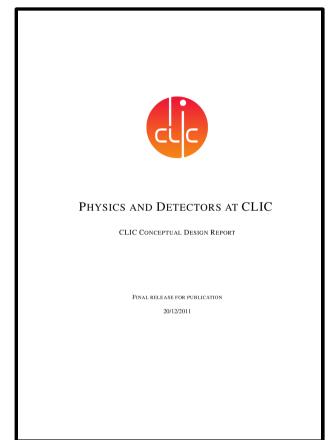
Challenging machine environment

 \rightarrow detailed detector studies are needed

CLIC physics and detector CDR:

- Physics potential
- Demonstrate that the physics can be measured at CLIC

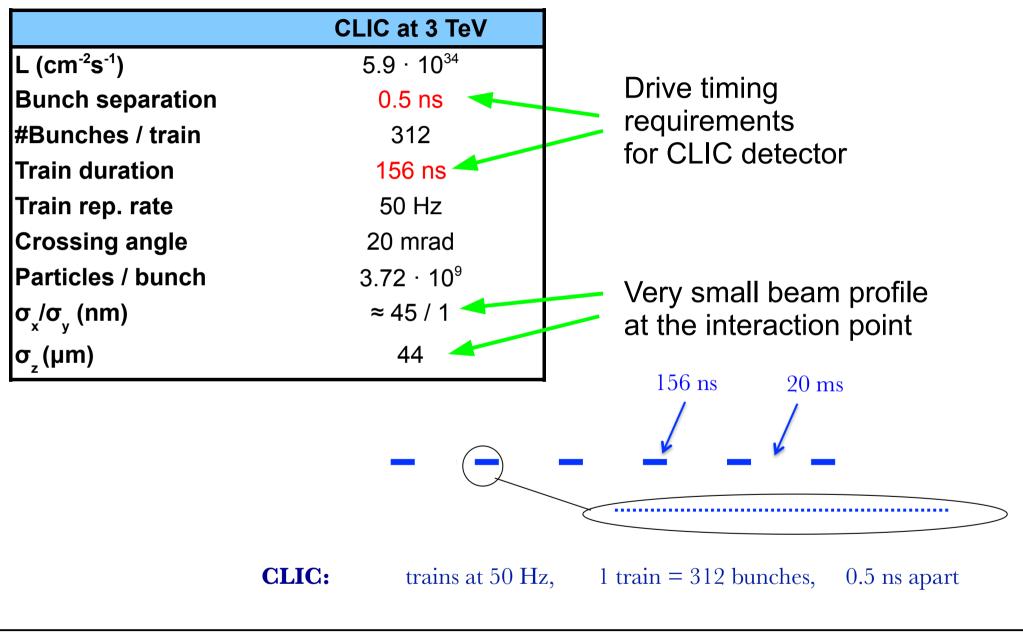
Release of the CDR text (20.12.2011): https://edms.cern.ch/document/1177771



Review in October 2011: https://indico.cern.ch/conferenceTimeTable.py?confld=146521



Selected CLIC parameters

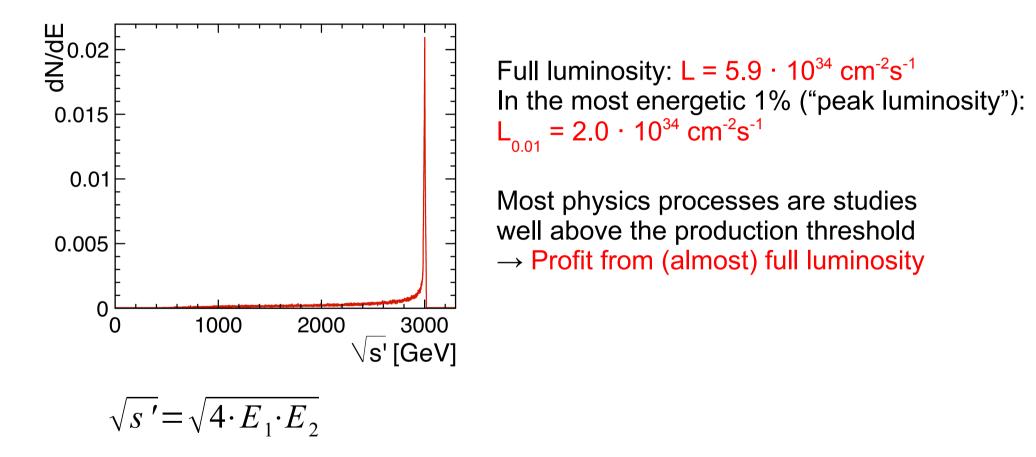


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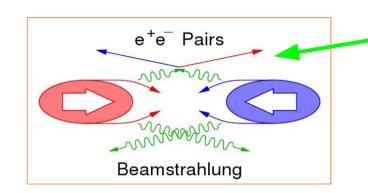
Significant energy loss at the interaction point due to **Beamstrahlung**

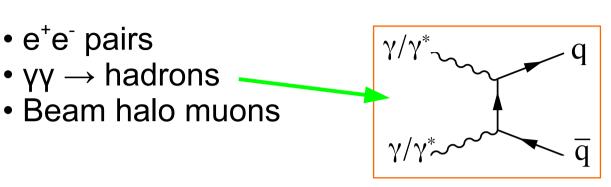




Beam related backgrounds





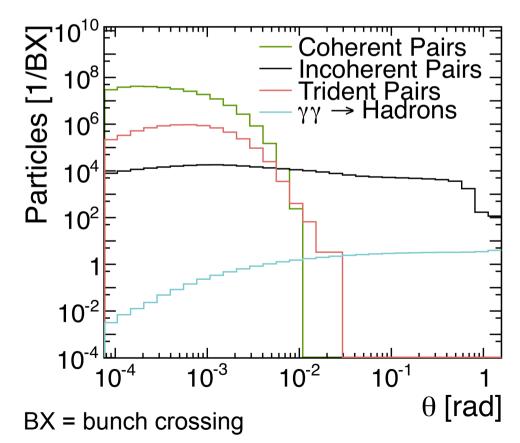


Coherent e^+e^- pairs: 7 · 10⁸ per BX, very forward Incoherent e^+e^- pairs: 3 · 10⁵ per BX, rather forward \rightarrow Detector design issue (high occupancies)

$\gamma\gamma \rightarrow hadrons$

• "Only" 3.2 per BX

- Main background in calorimeters and trackers
- \rightarrow Impact on physics







Physics at CLIC

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CLIC physics potential

 10^{3}

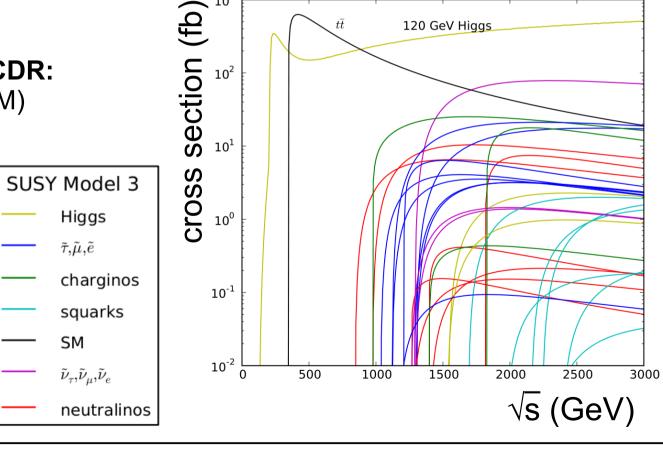
Advantage of e⁺e⁻ collisions:

- Defined initial state
- Precision measurements possible due to clean conditions
- Well suited for weakly interacting states (e.g. sleptons, gauginos)
- Polarised (electron) beam

→ Complementary / enhanced discovery reach compared to the LHC

Examples highlighted in the CDR:

- Higgs physics (SM and non-SM)
- Top physics
- SUSY
- Higgs strong interactions
- 7'
- Contact interactions
- Extra dimensions



 $t\bar{t}$

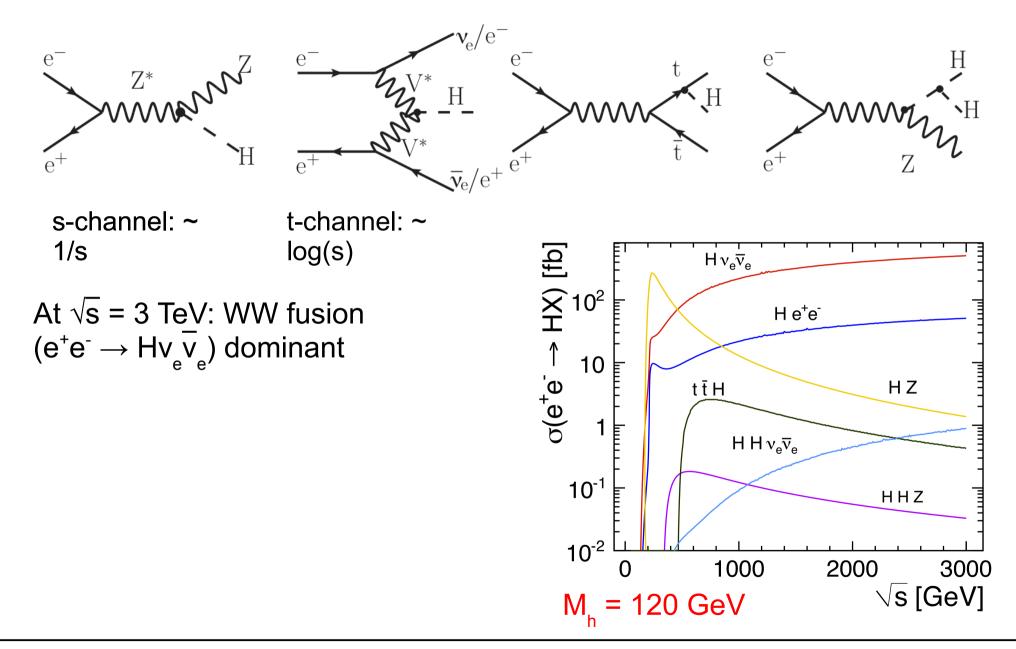
120 GeV Higgs





SM Higgs production

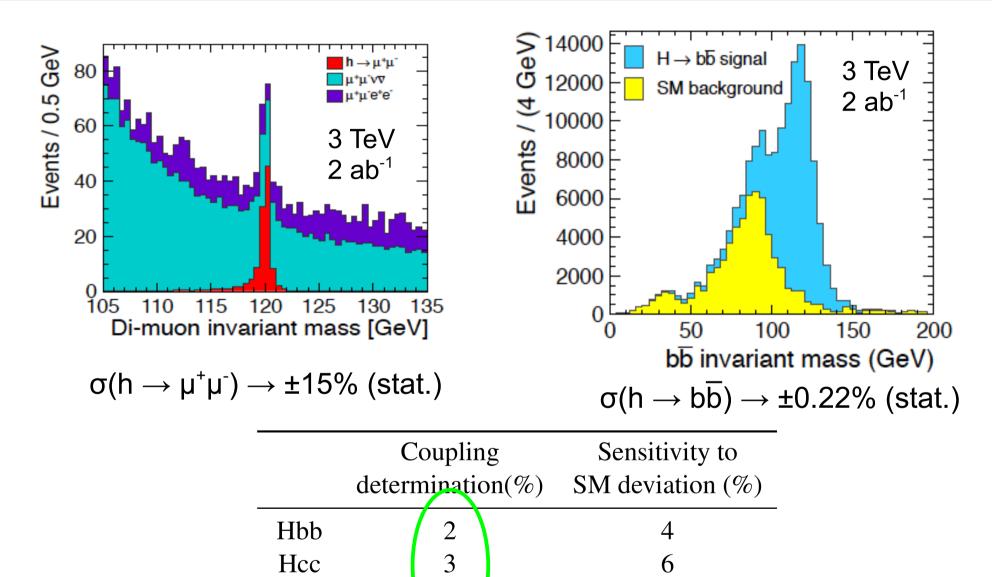






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Example Higgs observables



15

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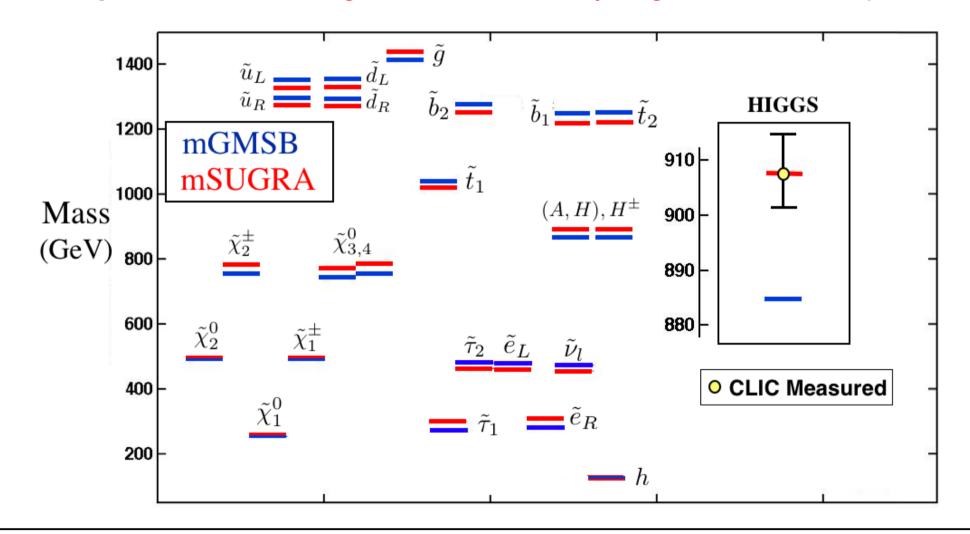
15

Ημμ



Resolving new physics models

Precision measurements at CLIC allow to discriminate between new physics models, e.g. following first observations at the LHC **Example:** SUSY breaking models with nearly degenerate mass spectra







Detector requirements

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Momentum resolution

(e.g. Higgs recoil mass, $h \rightarrow \mu^+ \mu^-$, leptons from BSM processes)

$$\frac{\sigma(p_T)}{p_T^2} \sim 2 \times 10^{-5} \, GeV^{-1}$$

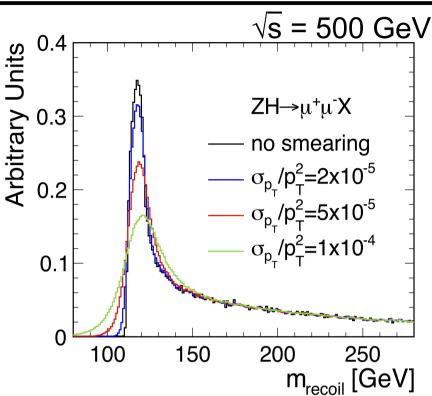
• Jet energy resolution (e.g. W/Z/h separation)

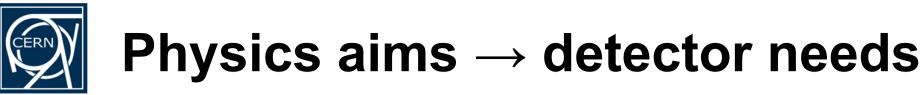
$$\frac{\sigma(E)}{E} \sim 3.5 - 5\%$$
 for $E = 1000 - 50 \, GeV$

• Impact parameter resolution (b/c tagging, e.g. Higgs couplings)

$$\sigma(d_0) = \sqrt{a^2 + b^2 \cdot GeV^2 / (p^2 \sin^3 \theta)}, a \approx 5 \, \mu m, b \approx 15 \, \mu m$$

Lepton identification, very forward electron tagging









Momentum resolution

(e.g. Higgs recoil mass, $h \rightarrow \mu^+ \mu^-$, leptons from BSM processes)

$$\frac{\sigma(p_T)}{p_T^2} \sim 2 \times 10^{-5} \, GeV^{-1}$$

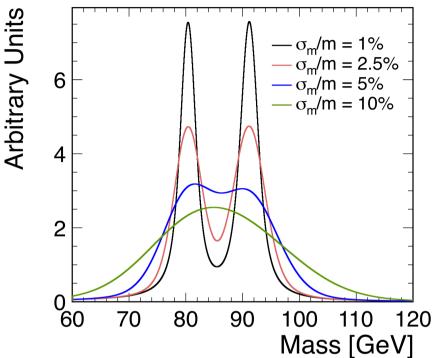
• Jet energy resolution (e.g. W/Z/h separation)

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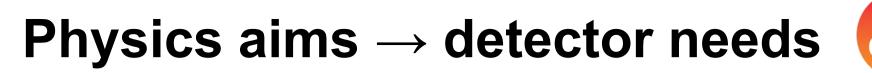
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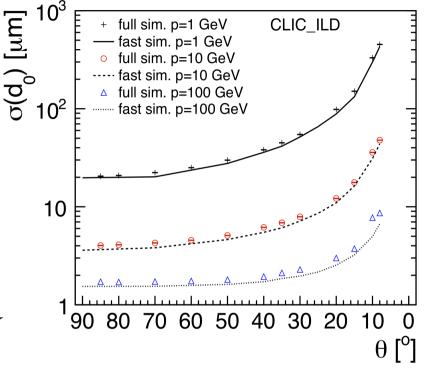
$$\frac{\sigma(E)}{E} \sim 3.5 - 5\%$$
 for $E = 1000 - 50 \, GeV$

Impact parameter resolution

(b/c tagging, e.g. Higgs couplings)

$$\sigma(d_0) = \sqrt{a^2 + b^2 \cdot GeV^2/(p^2 \sin^3 \theta)}, a \approx 5 \, \mu m \, , b \approx 15 \, \mu m$$

Lepton identification, very forward electron tagging



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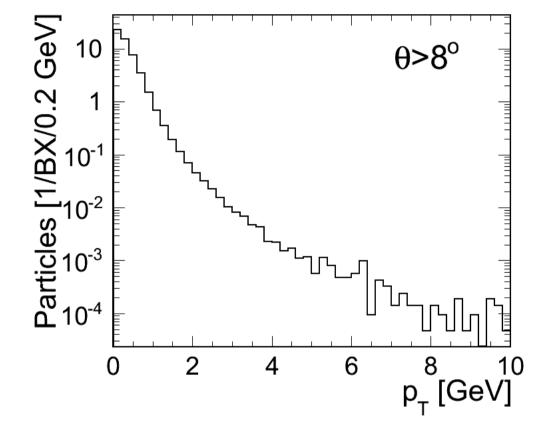


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General readout considerations

3.2 $\gamma\gamma \rightarrow$ hadr. Interactions per bunch crossing:

- 19 TeV in the calorimeters per 156 ns bunch train
- 5000 tracks with a total momentum of 7.3 TeV



Triggerless readout of full bunch train:

- Time-stamping in tracking detectors and calorimeters
- Multi-hit storage / readout
- Filtering algorithms at reconstruction level (\rightarrow later)





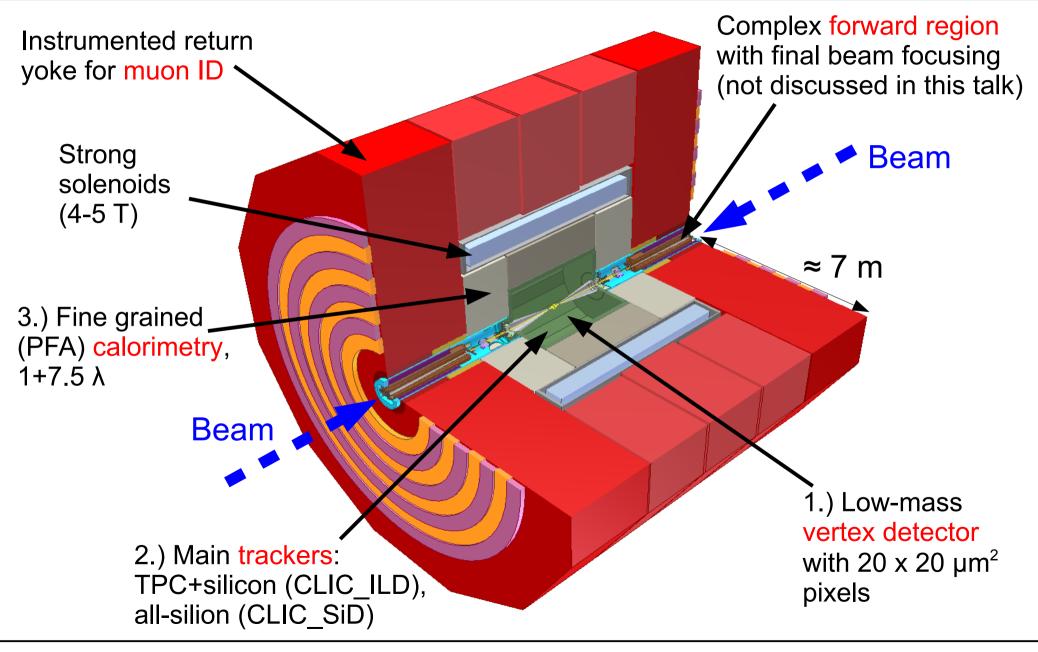
The CLIC_ILD and CLIC_SiD detectors

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Detector overview





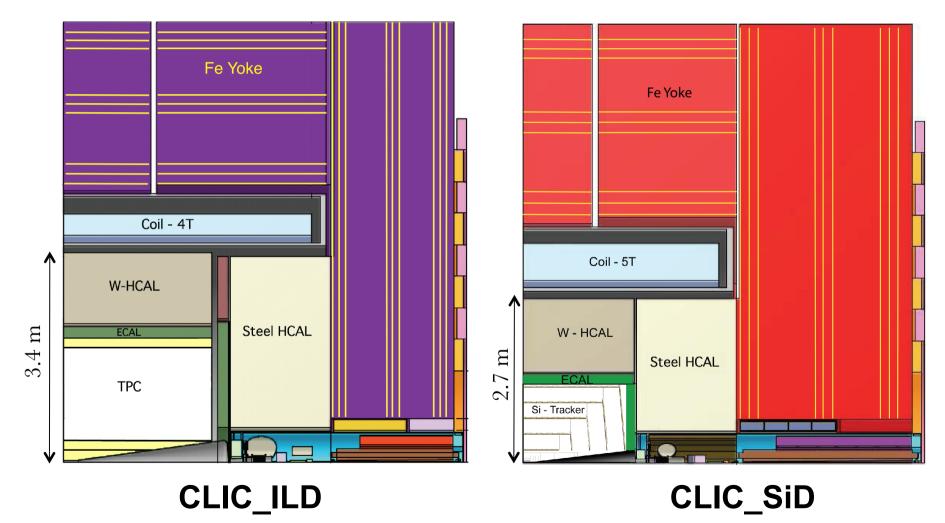


CLIC detector concepts



Based on validated ILC designs, adapted and optimised to the CLIC conditions:

- Denser HCAL in the barrel (Tungsten, 7.5 λ)
- Redesign of the vertex and forward detectors (backgrounds)







Vertex detectors

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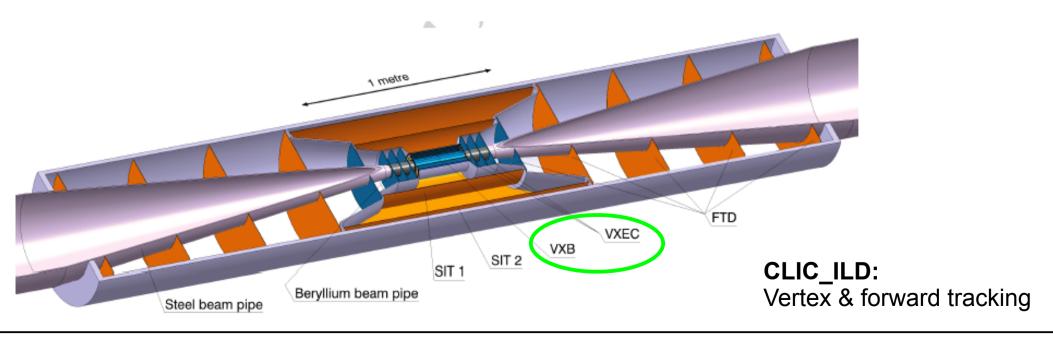


Vertex detector



Requirements:

- 20 x 20 µm² pixel size
- Material: 0.2% X_o per layer:
 - Very thin materials / sensors
 - Low-power design, power pulsing, low-mass cooling
- Time stamping precision: 5 10 ns (to reject backgrounds)
- Radiation level: ≈10¹⁰ n_{eq} /cm² /yr (10⁻⁴ of LHC)



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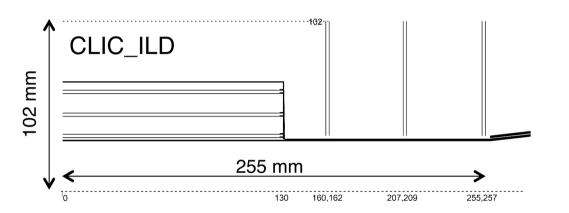


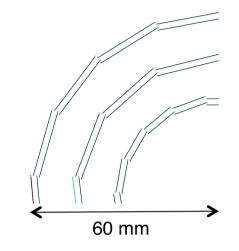
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Vertex detector layouts

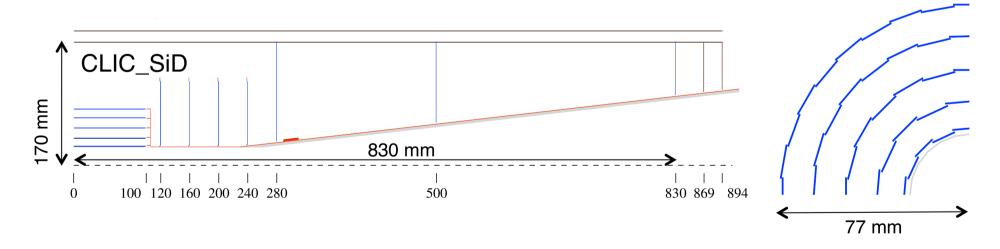






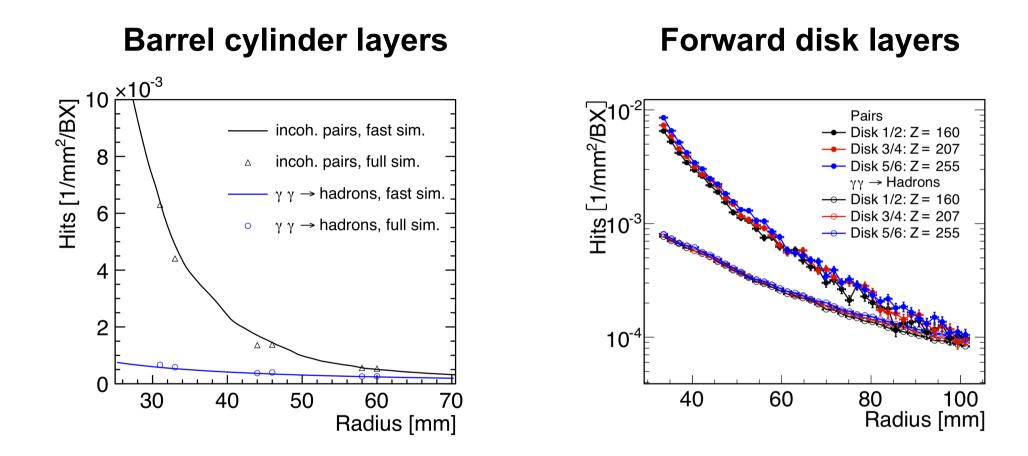


CLIC_SiD: 5 single layers, $2.76 \cdot 10^9$ pixels









- Direct hits from incoherent e⁺e⁻ pairs dominate
- Barrel: up to 1.9% train occupancy / pixel
- Forward: up to 2.9% train occupancy / pixel (including safety factors for simulation uncertainty and clustering)



Vertex detector cooling



Vertex detector: $P \approx 500 \text{ W} \rightarrow \text{need low mass cooling solutions}$

Forced (dry) air flow:

- Baseline for barrel region
- No extra material
- Up to 240 liter/s flow,
- ≈ 40 km/h flow velocity

Options in forward disks:

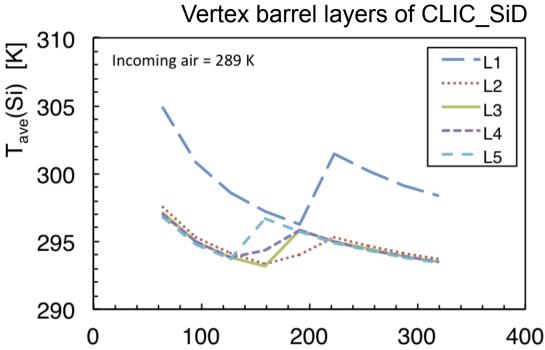
• Evaporative CO₂ cooling

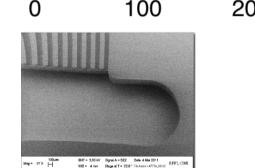
(high pressure \rightarrow thick tubes)

• Water cooling (sub-atmospheric pressure)

Micro-channel cooling:

- Ongoing R&D (e.g. NA62 upgrade)
- Integrate cooling channels in Silicon
- May be suitable for regions where sufficient air flow can not be established





Total Flow [g/s]

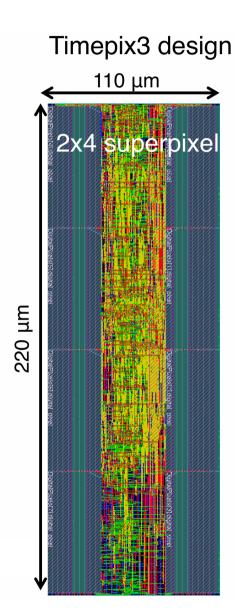


Pixel sensor options I



1.) Hybrid technologies:

- Thinned high-resistivity fully depleted sensors
- Fast, low-power highly integrated readout chip
- Low mass interconnects
- **Pros:** Factorisation of sensor + readout R&D
 - \rightarrow Readout chips profit fully from advancing industry standards
- **Cons:** Interconnect difficult / expensive \rightarrow needs R&D
 - Harder to reduce material
- Thinned high-resistivity fully depleted sensors:
 - 50 µm active thickness
 - ALICE pixel upgrade \rightarrow meets CLIC goals
- Fast low-power readout chips:
 - Timepix3 (2012) in 130 nm IBM CMOS:
 - 55 x 55 μ m² pixels
 - 1.5 ns time resolution \rightarrow exceeds CLIC goals
 - P \approx 10 μ W / pixel
 - CLICPix (prototypes ≈2014) in 65 nm, 20 x 20 µm² pixels





Pixel sensor options II



2.) Integrated technologies:

- Sensor and readout combined in one chip
- Charge collection in epitaxial layer
- **Pros:** Allows for very low material solutions
 - Synergy with R&D for ILC detectors
- **Cons:** Harder to achieve good time resolution and sufficient S/N
- Several active R&D programs (targeted to ILC requirements)
- Attempts to reach faster signal collection and ns time-stamping capability (compatible with CLIC requirements):
 - MIMOSA CMOS with high-resistivity epitaxial layers
 - Chronopixel CMOS
 - INMAPS
 - High voltage CMOS

3.) New technologies:

- Silicon-On-Insulator (SOI)
 - Full 3D-integrated pixel sensors





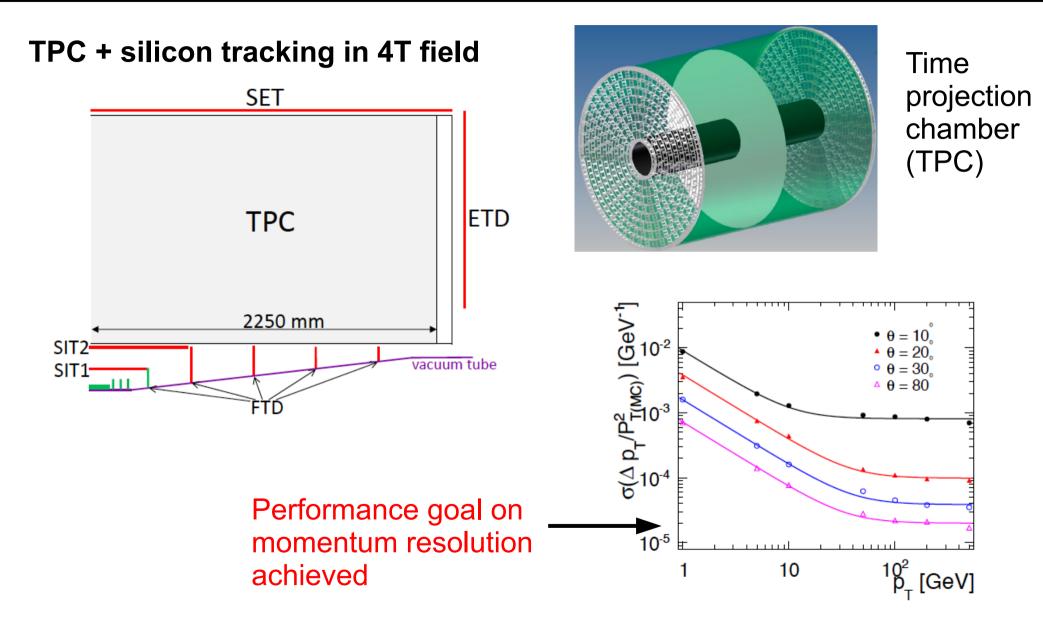
Tracking

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Tracking in CLIC_ILD



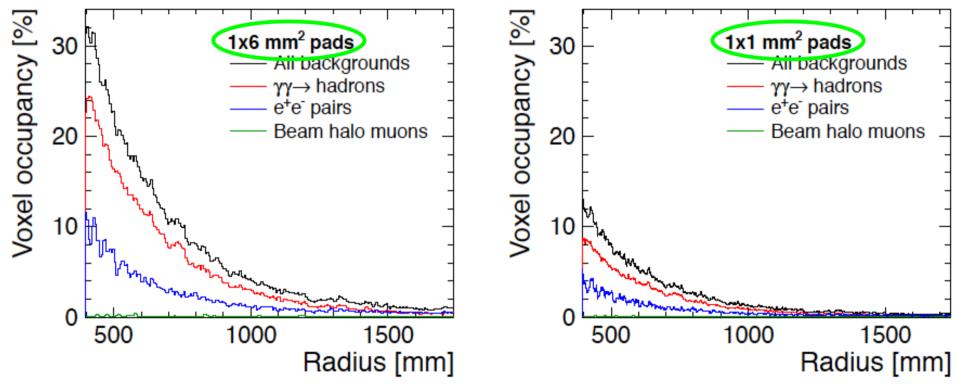




Occupancies in the TPC



The readout time of the TPC is much longer than a CLIC bunch train \rightarrow The TPC integrates the background of a full train at CLIC



Plots are for Gas Electron Multiplier (GEM) + Pad readout, voxels of 25 ns

 \rightarrow A TPC at CLIC may need a larger inner radius or very small pads Similar study with micromegas + pixel readout is starting



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Tracking in CLIC_SiD

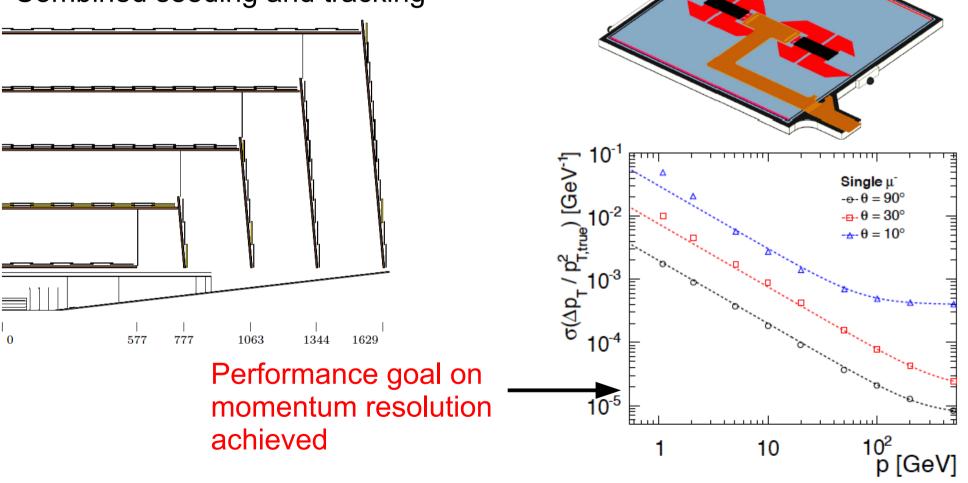


Two readout (KPiX) chips bump

bonded to the sensor



- Vertex detector and tracker viewed as one system
- Combined seeding and tracking







Calorimetry





Detector design driven by jet energy resolution and background rejection \rightarrow Fine-grained calorimetry + particle flow analysis (PFA)

What is **PFA**?

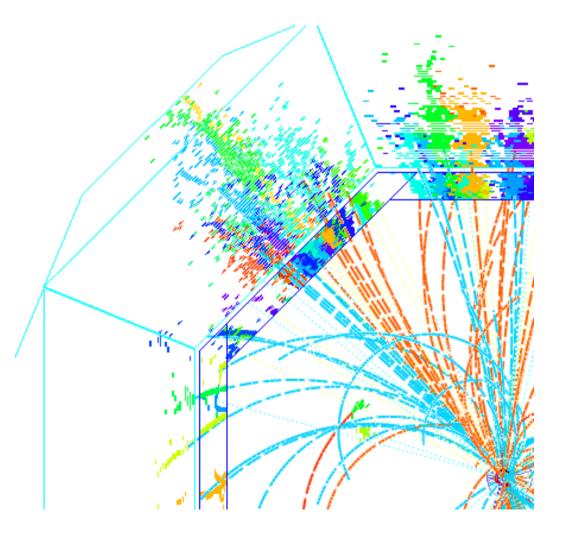
Typical jet composition:

- 60% charged particles
- 30% photons
- 10% neutral hadrons

Always use the best available measurement:

- charged particles
- \rightarrow tracking detectors: \bigcirc
- photons \rightarrow ECAL: \bigcirc
- neutrals \rightarrow HCAL: $\stackrel{\bullet}{\sim}$

Hardware and software!





Calorimetry: technology



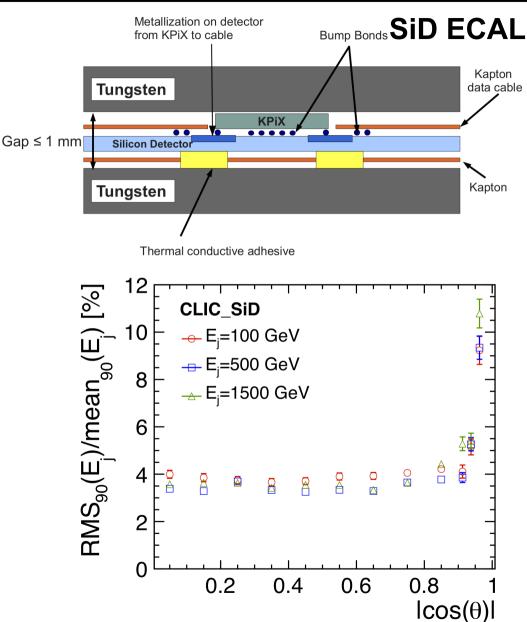
ECAL:

- Silicon pads or scintillator
- Tungsten absorber
- Cell sizes: 25 mm² (CLIC_ILD) 11 mm² (CLIC_SiD)
- 30 layers in depth
- 23 X_0° and 1 λ

HCAL:

- Several options for sensors
- Tungsten (barrel), steel (forward)
- Cell sizes: 9 cm² (analog) 1 cm² (digital)
- 60 75 layers in depth
- 7.5 λ

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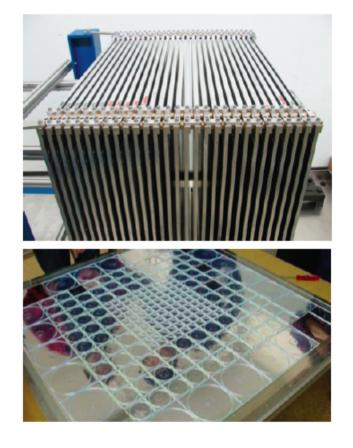


Tungsten HCAL prototype

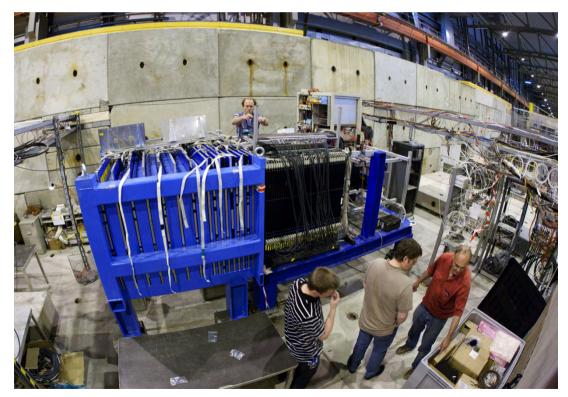


Main purpose: Validation of Geant4 simulation for hadronic showers in tungsten



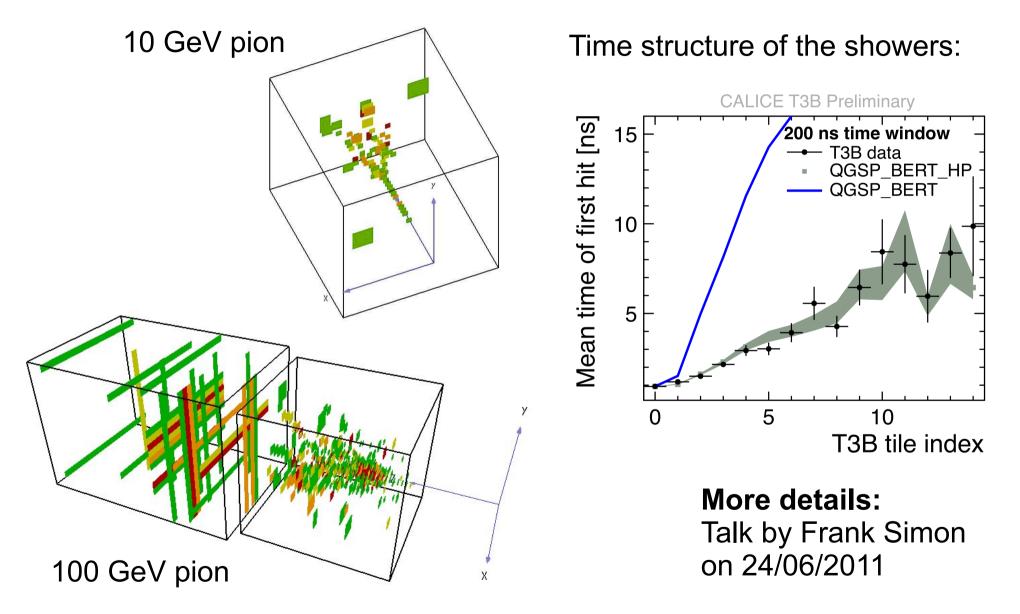


Scintillator tiles 3x3 cm² Read out by SiPM Data taken 2010/11 at CERN-PS/SPS, mixed beams 1-300 GeV





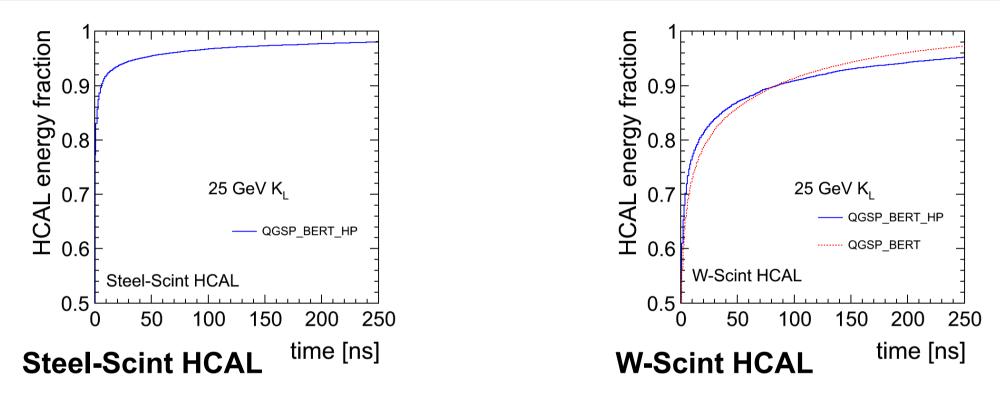






Time development in hadronic showers





- In steel 90% of the energy is recorded within 6 ns (corrected for time-of-flight)
- In tungsten only 82% of the energy is deposited within 25 ns:
- (much larger component of the energy in nuclear fragments)
- \rightarrow Energy resolution degrades if not the majority of calorimeter hits is read

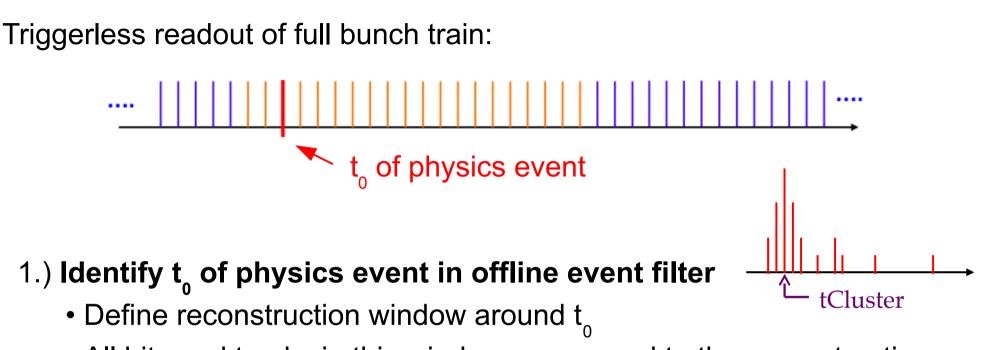
 \rightarrow Need to integrate over $\approx \! 100$ ns in the reconstruction, keeping the background level low





Background suppression and event reconstruction





• All hits and tracks in this window are passed to the reconstruction \rightarrow Physics objects with precise p₊ and cluster time information

2.) Apply cluster-based timing cuts

- Cuts depend on particle-type, $\textbf{p}_{_{T}}$ and detector region
- \rightarrow Protects physics objects at high p₁





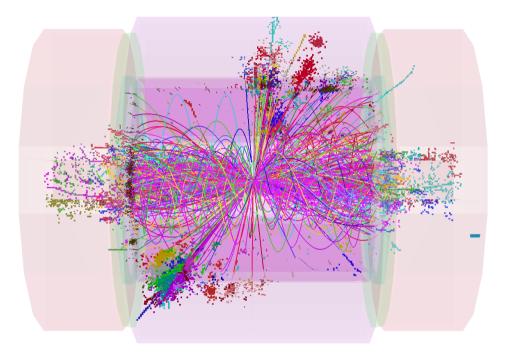
Used in the reconstruction software for CDR simulations:

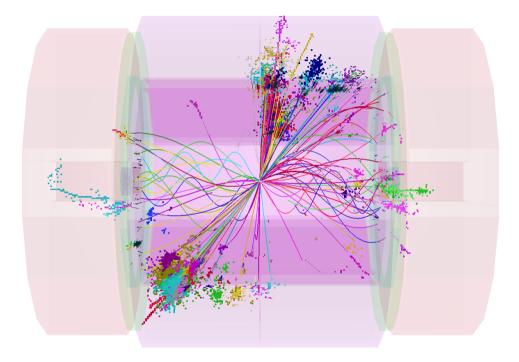
Subdetector	Reconstruction window	hit resolution	
ECAL	10 ns	1 ns	
HCAL Endcaps	10 ns	1 ns	
HCAL Barrel	100 ns	🗾 1 ns	
Silicon Detectors	10 ns	$10/\sqrt{12}$ ns	
TPC	entire bunch train	n/a	
	 CLIC hardware requirements Achievable in the calorimeters with a sampling every ≈ 25 ns 		





$e^+e^- \rightarrow H^+H^- \rightarrow t\overline{b}b\overline{t}$ (8 jet final state)



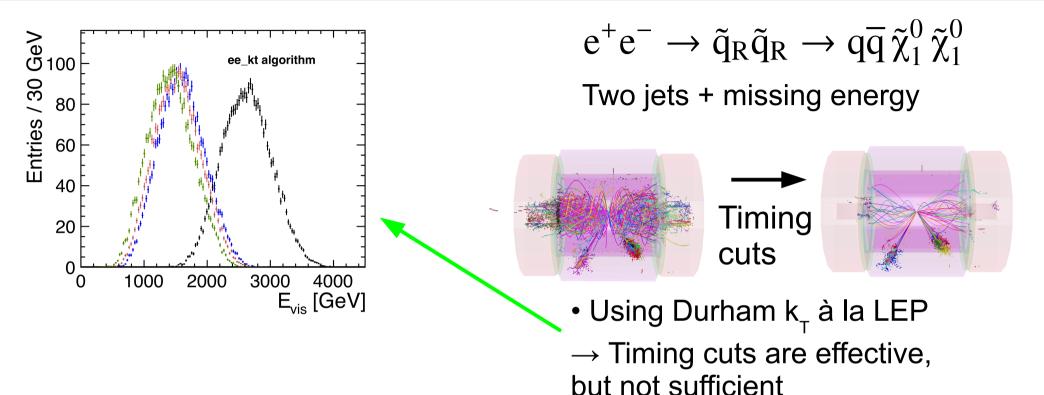


1.2 TeV background in the reconstruction window

100 GeV background after (tight) timing cuts

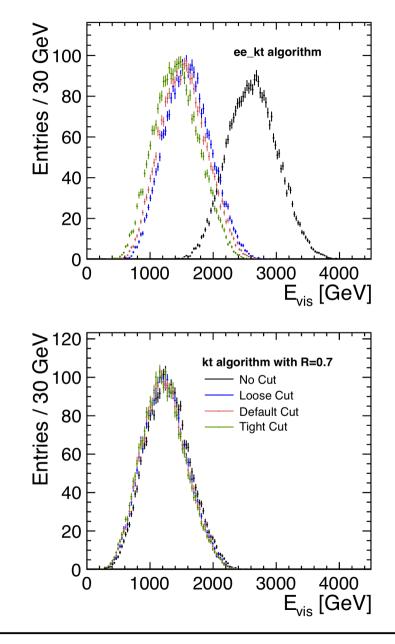


Jet reconstruction at CLIC I



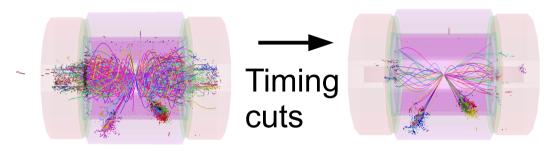


Jet reconstruction at CLIC II



 $e^+e^- \to \tilde{q}_R \tilde{q}_R \to q \overline{q} \, \tilde{\chi}^0_1 \, \tilde{\chi}^0_1$

Two jets + missing energy



- Using Durham k_⊤ à la LEP
 → Timing cuts are effective, but not sufficient
- "hadron collider" k_{T} , R = 0.7
- \rightarrow Background significantly reduced further

 \rightarrow Need timing cut + jet finding for background reduction



Test of the di-jet mass reconstruction

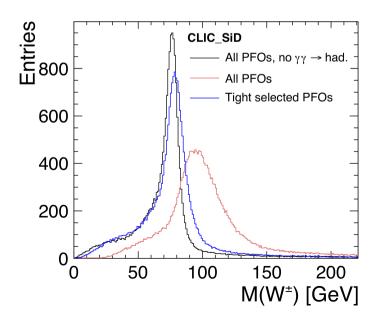
Chargino and neutralino pair production:

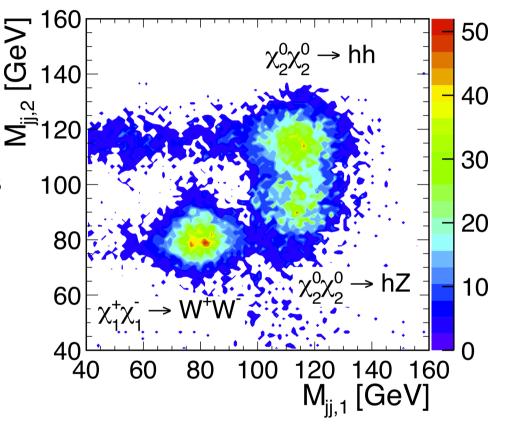
$$e^{+}e^{-} \rightarrow \tilde{\chi}_{1}^{+}\tilde{\chi}_{1}^{-} \rightarrow \tilde{\chi}_{1}^{0}\tilde{\chi}_{1}^{0}W^{+}W^{-}$$

$$e^{+}e^{-} \rightarrow \tilde{\chi}_{2}^{0}\tilde{\chi}_{2}^{0} \rightarrow hh\tilde{\chi}_{1}^{0}\tilde{\chi}_{1}^{0} \qquad 82\%$$

$$e^{+}e^{-} \rightarrow \tilde{\chi}_{2}^{0}\tilde{\chi}_{2}^{0} \rightarrow Zh\tilde{\chi}_{1}^{0}\tilde{\chi}_{1}^{0} \qquad 17\%$$

Reconstruct $W^{\pm}/Z/h$ in hadronic decays \rightarrow four jets and missing energy





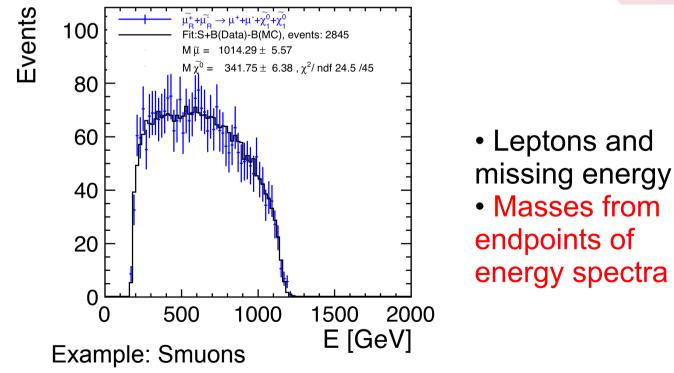


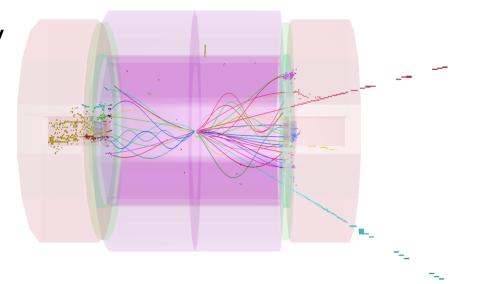
Test of the lepton reconstruction



- Slepton production very clean at CLIC
- SUSY "model II": slepton masses ≈ 1 TeV
- Investigated channels include:

$$\begin{split} e^+e^- &\rightarrow \tilde{\mu}^+_R \tilde{\mu}^-_R \rightarrow \mu^+ \mu^- \tilde{\chi}^0_1 \tilde{\chi}^0_1 \\ e^+e^- &\rightarrow \tilde{e}^+_R \tilde{e}^-_R \rightarrow e^+e^- \tilde{\chi}^0_1 \tilde{\chi}^0_1 \\ e^+e^- &\rightarrow \tilde{\nu}_e \tilde{\nu}_e \rightarrow e^+e^- W^+ W^- \tilde{\chi}^0_1 \tilde{\chi}^0_1 \end{split}$$





$m(\tilde{\mu}_R)$:	$\pm 5.6 \text{GeV}$
$m(\tilde{e}_{R})$:	$\pm 2.8\mathrm{GeV}$
$m(\tilde{v}_e)$:	$\pm 3.9 \text{GeV}$
$m(\tilde{\chi}_1^0)$:	$\pm 3.0 \text{GeV}$
$m(\tilde{\chi}_1^{\pm})$:	$\pm 3.7 \text{GeV}$





12.4	Detector Benchmark Processes	12
12.4.1	Light Higgs Decays to Pairs of Bottom and Charm Quarks	13
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	6 Chargino and Neutralino Production at 3 TeV	
12.4.7	Top Pair Production at 500 GeV	34

• Full physics simulation and reconstruction with pileup from beam background ($\gamma\gamma \rightarrow$ hadr.)

• Seven channels chosen to cover various crucial aspects of detector performance (jet measurements, missing energy, isolated leptons, flavour tagging, ...)





- Main message of the CLIC physics and detector CDR: Physics at a 3 TeV CLIC e⁺e⁻ collider can be measured with high precision, despite challenging background conditions
- Backgrounds studied in detail:
 - Require high granularity in space and time
 - Define detector requirements and guide future R&D
- Next project phase (5 years):
 - CLIC detector R&D (within the international LC R&D program)
 - Further physics studies (LHC input) + detector optimisation
- Signatories to support the physics case and R&D towards a future linear collider based on CLIC technology are currently collected here:

https://indico.cern.ch/conferenceDisplay.py?confld=136364





Backup slides

Examples for hybrid approach

Thinned high-resistivity fully depleted sensors:

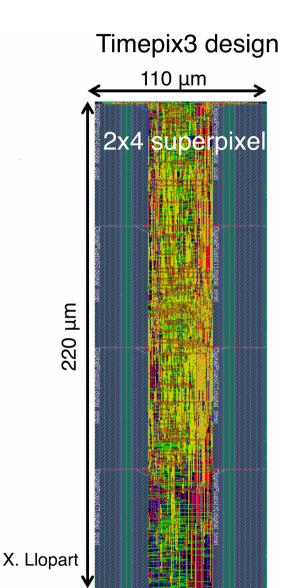
- 50 µm active width
- Example: ALICE pixel upgrade → meets CLIC goals

Fast low-power readout chips:

- Timepix3 (2012) in 130 nm IBM CMOS:
 - 55 x 55 μ m² pixels
 - 1.5 ns time resolution \rightarrow exceeds CLIC goals
 - P \approx 350 mW / cm² \rightarrow meets CLIC goals (with power pulsing)
- CLICPix (prototypes ≈2014) in 65 nm:
 - 20 x 20 μ m² pixels

Low-mass interconnects between senor+readout:

- Cost driver \rightarrow needs further R&D
- Technologies: Through-Silicon Vias (TSV),
- 3D interconnects, edgeless sensors, stitching of CMOS arrays









- Several active R&D programs (targeted to ILC requirements)
- Attempts to reach faster signal collection and ns time-stamping capability (compatible with CLIC requirements):
 - MIMOSA CMOS chip family (currently 350 nm):
 - developing high-resistivity epitaxial layers, smaller feature sizes
 - Chronopixel CMOS sensors with fully depleted epitaxial layer
 - **INMAPS** technology: deep p-well barrier protects n-well charge collector, improves charge collection, allows for high-resistivity epitaxial layer and full featured CMOS MAPS technology
 - High voltage CMOS: CMOS signal processing electronics embedded in reverse-biased deep n-well that acts as signal collecting electrode
 - Silicon-On-Insulator (SOI): ≈200 nm SiO₂ isolation layer separates

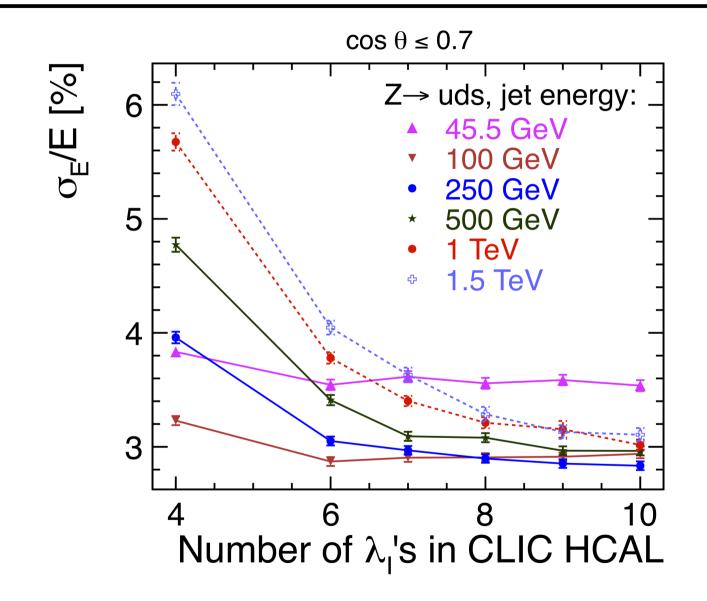
charge collection and readout functionality

- Full 3D-integrated pixel sensors: Thinned high-resistivity sensitive tier coupled to additional tiers with advanced analog+digital functionality



HCAL resolution







PFO based timing cuts

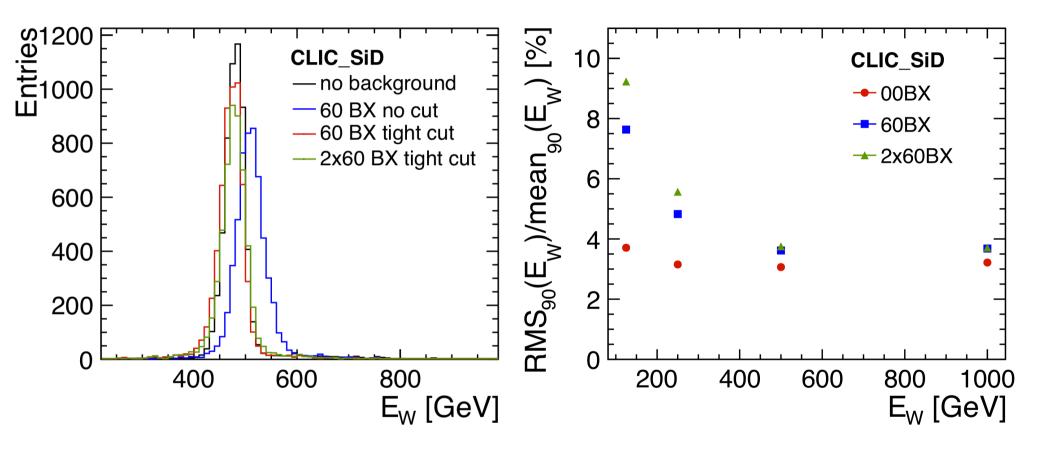


Region	p _t range	Time cut		
Photons				
central	$0.75~{ m GeV} \le p_t < 4.0~{ m GeV}$	t < 2.0 nsec		
$(\cos\theta \le 0.975)$	$0~{ m GeV} \le p_t < 0.75~{ m GeV}$	t < 1.0 nsec		
forward	$0.75~{ m GeV} \le p_t < 4.0~{ m GeV}$	t < 2.0 nsec		
$(\cos \theta > 0.975)$	$0~{ m GeV} \le p_t < 0.75~{ m GeV}$	t < 1.0 nsec		
Neutral hadrons				
central	$0.75~{ m GeV} \le p_t < 8.0~{ m GeV}$	t < 2.5 nsec		
$(\cos\theta \le 0.975)$	$0~{ m GeV} \le p_t < 0.75~{ m GeV}$	t < 1.5 nsec		
forward	$0.75~{ m GeV} \le p_t < 8.0~{ m GeV}$	t < 2.0 nsec		
$(\cos \theta > 0.975)$	$0~{ m GeV} \le p_t < 0.75~{ m GeV}$	t < 1.0 nsec		
Charged PFOs				
all	$0.75~{ m GeV} \le p_t < 4.0~{ m GeV}$	t < 3.0 nsec		
	$0~{ m GeV} \le p_t < 0.75~{ m GeV}$	<i>t</i> < 1.5 nsec		

- Track-only minimum p_t: 0.5 GeV
- Track-only maximum time at ECAL: 10 nsec











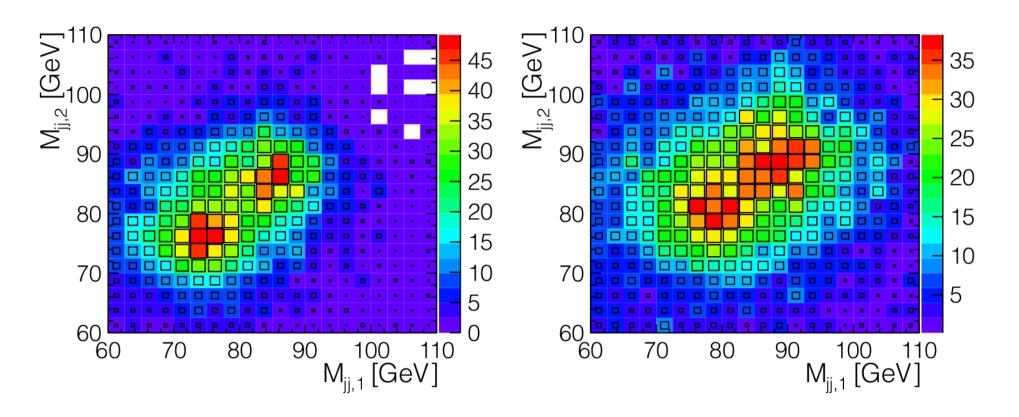


Figure 19: Separation of *W* and *Z* from the chargino decay without overlay (left) and with 60 BX of background (right) for CLIC_SiD.